Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L6	1	"20020020898".PN.	US-PGPUB	OR	ON	2004/12/06 10:20
L7	1	"6110806".PN.	USPAT; USOCR	OR	ON	2004/12/06 10:22
L8	1	"6010956".PN.	USPAT; USOCR	OR	ON	2004/12/06 10:22
L9	1	"5757072".PN.	USPAT; USOCR	OR	ON	2004/12/06 10:22
L10	1	"5353498".PN.	USPAT; USOCR	OR	ON	2004/12/06 10:23
L13	3	@ad<="20030909" and 'C4' same 'thick metal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/06 11:06
L15	172	@ad<="20030909" and 'C4' with 'connection' with 'metal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/06 12:02
L20	1	@ad<="20030909" and 'orthorgonal' same 'connection'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/06 12:06
L22	772	@ad<="20030909" and 'interconnection' same 'metal layer' with 'barrier'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/06 12:07
L23	52	@ad<="20030909" and 'interconnection' same 'metal layer' with 'diffusion barrier'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/06 12:15
L24	953	@ad<="20030909" and 'metal layer' with 'diffusion barrier'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/06 12:15
S1	1120	@ad<="20030909" and (257/734).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 14:13
S2	1413	@ad<="20030909" and 'controlled collapse chip connection'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/06 11:05

S3	1	@ad<="20030909" and 'controlled collapse chip connection' same 'interconnection' and 'thick metal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:27
S4	277	@ad<="20030909" and 'controlled collapse chip connection' same 'interconnection'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 14:31
S5	5310	@ad<="20030909" and (257/690). ccls. or (257/700).ccls. or (257/737).ccls. or (257/788).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/06 09:09
S6	50	@ad<="20030909" and 'controlled collapse chip connection' and 'interconnection' same 'metal layers'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 14:31
S7	91	@ad<="20030909" and 'flip chip' same 'interconnection' same 'metal layers'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 14:31
S8	8889	@ad<="20030909" and (257/778). ccls. or (257/691-692).ccls. or (257/758-760).ccls. or (257/738). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 14:58
S9	560	@ad<="20030909" and 'metal' same 'interconnection' same 'bump' same 'pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:39
S10	2	@ad<="20030909" and 'thick metal' same 'interconnection' same 'bump' same 'pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:28
S11	14	@ad<="20030909" and 'metal' same 'interconnection' same 'bump' same 'pad' same 'current'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:34
S12	1	@ad<="20030909" and 'interconnection' same 'bump' same 'large current'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:35
S13	313	@ad<="20030909" and 'interconnection' same 'large current'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:35

S14	2	@ad<="20030909" and 'interconnect' same 'large current' same 'bump'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:35
S15	201	@ad<="20030909" and 'metal' with 'interconnection' same 'bump' with 'pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:40
S16	1413	@ad<="20030909" and 'controlled collapse chip connection'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:40
S17	20	S16 and 'metal' with 'interconnection' same 'bump' with 'pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:42
S18	348	S16 and 'interconnection' same 'bump'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:42
S19	300	S16 and 'interconnection' same 'bump' and 'metal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:43
S20	117	S16 and 'interconnection' same 'bump' same 'metal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:43
S21	48	S16 and 'interconnection' same 'bump' same 'metal' and 'IC'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:43
S22	4840	@ad<="20030909" and (257/701). ccls. or (257/773).ccls. or (257/E23.021).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/06 09:10
S23	1490	@ad<="20030909" and (257/E23. 069).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/06 09:11